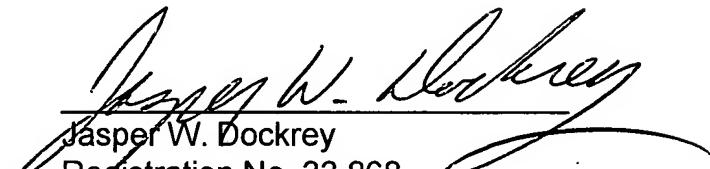


**REMARKS**

The applicants respectfully request entry of the amendment prior to commencing examination of the application.

Respectfully submitted,

  
\_\_\_\_\_  
Jasper W. Dockrey  
Registration No. 33,868  
Attorney for Applicants

BRINKS HOFER GILSON & LIONE  
P.O. BOX 10395  
CHICAGO, ILLINOIS 60610  
(312) 321-4200

## Amended Abstract

The invention relates to a lithography method involving the pressing of a substrate (1). The inventive method consists of the following steps: includes a preparation step during which the substrate is covered with a layer (2), a pressing step in which a mould (3) comprising including a pattern of recesses (5) and protrusions (4) is pressed ~~such as to penetrate~~ into part of the thickness of the aforementioned layer, at least one etching step in which the layer is etched until parts of the surface of the substrate have been stripped, and an a substrate etching step whereby the substrate is etched using an etching pattern which is defined from the mould pattern. The invention is characterised in that the The preparation step comprises: includes a sub-step consisting of including the formation of a lower sub-layer (2A) of curable material, a step involving the curing of said layer and a sub-step consisting of the formation of an outer sub-layer (2B) which is adjacent to the cured sub-layer. Moreover, during the pressing step, the above-mentioned protrusions in the mould penetrate the outer sub-layer until contact is reached with the cured sub-layer.